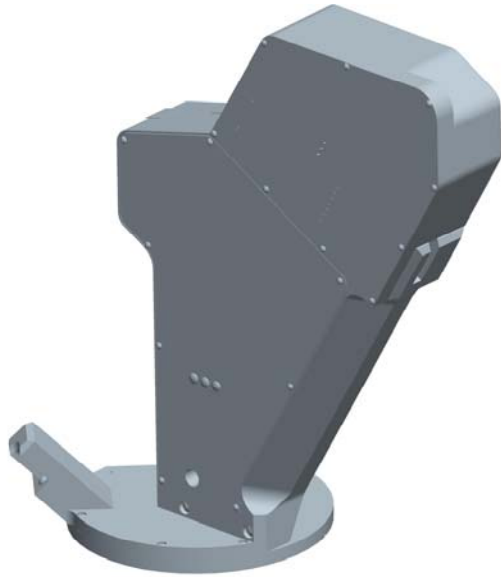




MicroPad™ Sensor for SE 300 Ultra

IN-LINE 100% INSPECTION SYSTEM



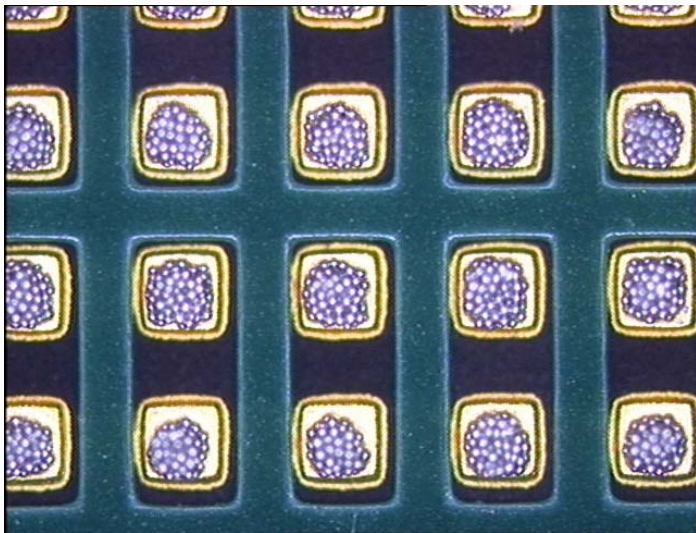
MicroPad Sensor

ENHANCED SENSOR PERFORMANCE FOR SMALL PASTE DEPOSITS

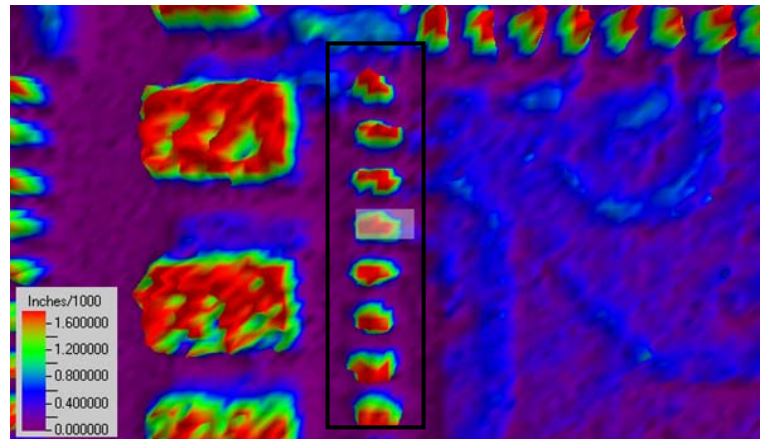
CyberOptics is building on its standard high-performance SE 300 Ultra system with a sensor option that offers even more to meet new challenges for solder paste inspection: high magnification of small solder paste pads.

The sensor is capable of measuring height, area, and volume on pads as small as 100 microns (4 mils) while maintaining Gage R&R less than 10%-ideal for batch inspection of system-on-chip and flip chip applications as well as NPI process qualification.

This sensor can be interchanged easily with a standard sensor so that you can operate in both modes with a single machine by simply exchanging the sensors.



140 x 140 micron pads



100 x 150 micron pads

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SPECIFICATIONS

X and Y Pixel Size High speed High resolution	20 microns (1.6 mils) 10 microns (0.79 mils)
Field of View	5 x 10 mm (0.2 x 0.39 in.)
Paste Height Range	50-355 microns (2-14 mils)
Height Resolution	0.125 microns (0.005 mils)
Maximum Board Warp	< 2% of PCB diagonal or 6.35 mm (0.25 in.) total
Maximum Pad Size in FOV	2.5 x 5 mm
Gage R&R	< 10% (high resolution)
Typical Inspection Speeds High Speed High Resolution Unload and fiducial find	8.4 sq. cm/sec (1.4 sq. in/sec) 4.8 sq. cm/sec (0.75 sq. in/sec) 5-7 seconds
Laser Range Finder (built into sensor)	640-870 nm, 1mW max, Class II

For More Information

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Data subject to change without notice.

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